

ABSTRACT OF THE DISCLOSURE

The present invention provides a method of mounting a semiconductor laser component capable of preventing deterioration of laser characteristics and destruction of the semiconductor laser component due to a rise in temperature and a residual stress of the semiconductor laser component, wherein the semiconductor laser component is mounted on a submount by heating and pressure-bonding, and is heated again up to a temperature more than a melting point of a bonding member at the released pressure to release the residual stress.